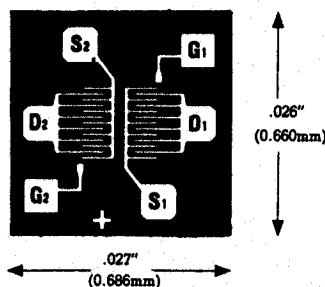


CHIP NUMBER

DMN36.1A



Die Size: .26 x .27 (mils)
0.660 x 0.686(mm)
3.5 x 3.5(mils)
Pad Size: 0.089 x 0.089(mm)

CONTACT METALLIZATION

Top Contact: > 12,000
Å Aluminum

Backside Contact: 3,000 Å Gold

ASSEMBLY RECOMMENDATIONS

It is advisable that:

- the die be eutectically mounted with gold silicon preform 98/2%.
- 1 mil (0.0254mm) aluminum wire be ultrasonically attached to the top contact.

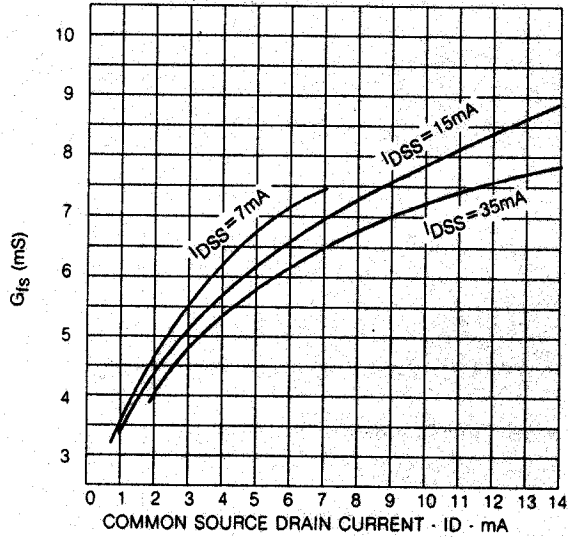
TYPICAL ELECTRICAL CHARACTERISTICS

PARAMETER	MIN.	TYP	MAX.	UNIT	TEST CONDITIONS
BVGSS	-25	-35		V	$V_{DS} = 0, I_G = I_{\mu A}$
I_{DSS}	5	20	40	mA	$V_{DS} = 10V, V_{GS} = 0$
V_p	-1		-6	V	$V_{DS} = 10V, I_D = 1nA$
I_{GSS}		10	100	pA	$V_{DS} = 0, V_{GS} = -15V$
g_{fs}	4.5	6.0	10	ms	$V_{DS} = 10V, I_D = 5mA, f = 1MHz$
C_{rss}		1.0	1.5	pF	$V_{DS} = 10V, I_D = 5mA, f = 1MHz$
$\bar{e}_n$		4	20	nV/√Hz	$V_{DS} = 10V, I_D = 5mA, f = 1KHz$

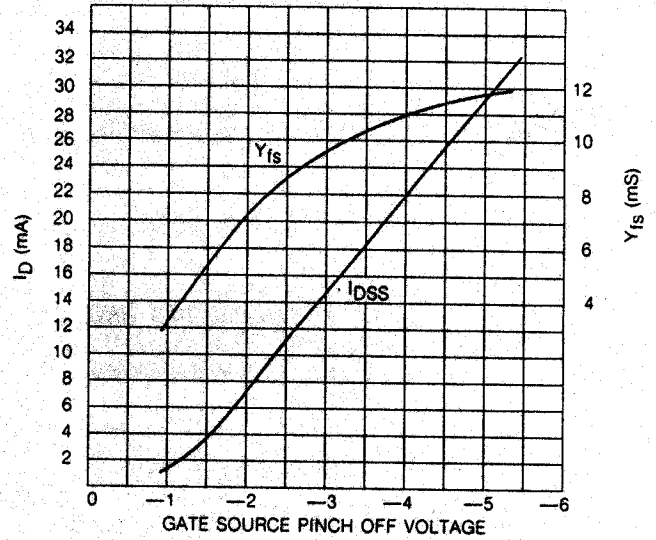
TYPICAL DEVICE TYPES: 2N5911, 2N5912, U257

CHIP TYPE DMN36.1A

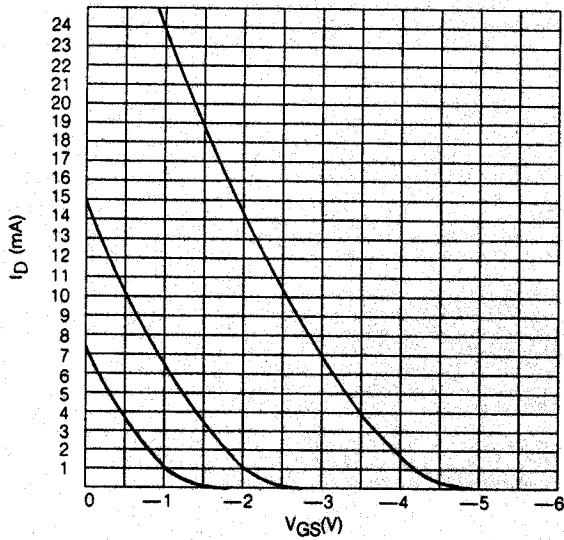
COMMON SOURCE, SHORT CIRCUIT FORWARD TRANSADMITTANCE
VS OPERATING DRAIN CURRENT



ZERO GATE VOLTAGE
DRAIN CURRENT · I_{DSS} · mA



TRANSFER CHARACTERISTIC



COMMON-SOURCE
DRAIN CHARACTERISTICS

